

10/500119

DT04 Rec'd PCT/PTO 25 JUN 2004
1204.43988X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. Nakamura, et al.

Application No.: TBD

Filed: June 25, 2004

For: CONNECTION BOARD, AND MULTI-LAYER WIRING BOARD,
SUBSTRATE FOR SEMICONDUCTOR PACKAGE AND
SEMICONDUCTOR PACKAGE USING CONNECTION
BOARD, AND MANUFACTURING METHOD THEREOF

Group: Unassigned

Examiner: Unassigned

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 25, 2004

Sir:

Please amend the above-identified application, prior to examination thereof,
as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the amendments.